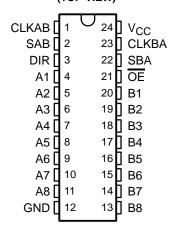
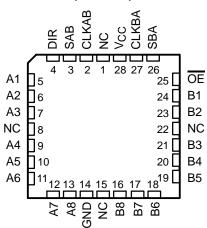
- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 11 ns

SN54HC646 ... JT OR W PACKAGE SN74HC646 ... DW OR NT PACKAGE (TOP VIEW)



- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Independent Registers for A and B Buses
- Multiplexed Real-Time and Stored Data
- True Data Paths

SN54HC646 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

description/ordering information

The 'HC646 devices consist of bus-transceiver circuits with 3-state outputs, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'HC646 devices.

Output-enable (\overline{OE}) and direction-control (DIR) inputs control the transceiver functions. In the transceiver mode, data present at the high-impedance port may be stored in either or both registers.

The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode) data. DIR determines which bus receives data when \overline{OE} is active (low). In the isolation mode (\overline{OE} high), A data may be stored in one register and/or B data may be stored in the other register.

ORDERING INFORMATION

TA	PACKAC	3E†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – NT	Tube	SN74HC646NT	SN74HC646NT
–40°C to 85°C	SOIC - DW	Tube	SN74HC646DW	HC646
	SOIC - DW	Tape and reel	SN74HC646DWR	ПС040
	CDIP – JT	Tube	SNJ54HC646JT	SNJ54HC646JT
–55°C to 125°C	CFP – W	Tube	SNJ54HC646W	SNJ54HC646W
	LCCC – FK	Tube	SNJ54HC646FK	SNJ54HC646FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SN54HC646, SN74HC646 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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description/ordering information (continued)

To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

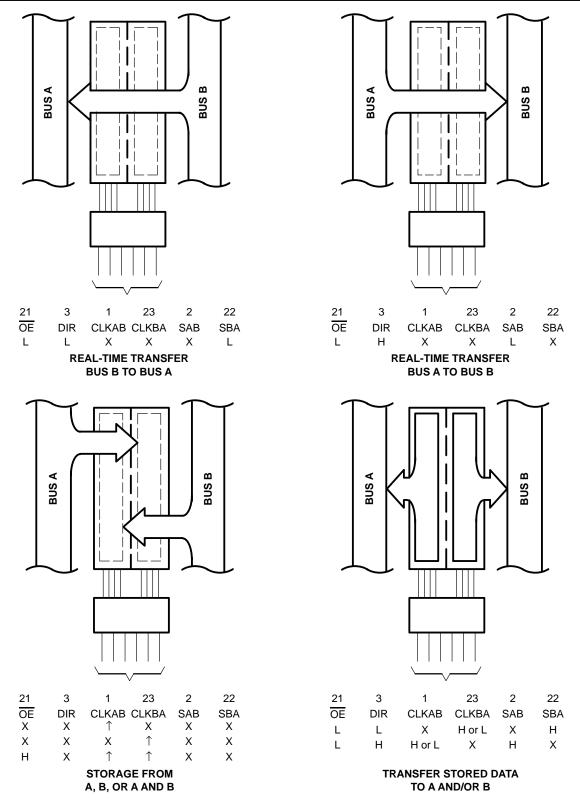
When an output function is disabled, the input function is still enabled and can be used to store data. Only one of the two buses, A or B, may be driven at a time.

FUNCTION TABLE

		INP	UTS			DAT	A I/O	OPERATION OR FUNCTION
OE	DIR	CLKAB	CLKBA	SAB	SBA	A1-A8	B1-B8	OPERATION OR FUNCTION
Х	Х	1	Х	Х	Х	Input	Unspecified [†]	Store A, B unspecified [†]
Х	X	Χ	\uparrow	X	Χ	Unspecified [†]	Input	Store B, A unspecified [†]
Н	Х	1	↑	Х	Х	Input	Input	Store A and B data
Н	Χ	H or L	H or L	Χ	Χ	Input disabled	Input disabled	Isolation, hold storage
L	L	Х	Х	Х	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	Х	Н	Output	Input	Stored B data to A bus
L	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus
L	Н	H or L	Х	Н	Χ	Input	Output	Stored A data to B bus

The data-output functions can be enabled or disabled by various signals at $\overline{\text{OE}}$ and DIR. Data-input functions always are enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.



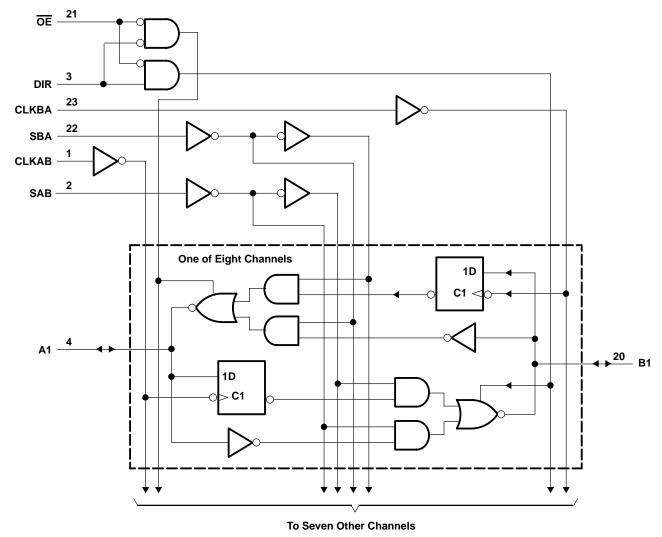


Pin numbers shown are for the DW, JT, NT, and W packages.

Figure 1. Bus-Management Functions



logic diagram (positive logic)



Pin numbers shown are for the DW, JT, NT, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V_{CC}	
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	
Continuous output current, I_O ($V_O = 0$ to V_{CC})	
Continuous current through V _{CC} or GND	±70 mA
Package thermal impedance, θ _{JA} (see Note 2): DW package	46°C/W
(see Note 3): NT package	67°C/W
Storage temperature range, T _{stg}	. −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-3.



recommended operating conditions (see Note 4)

			SN	154HC64	16	SN	174HC64	ŀ6	LINIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		2	5	6	2	5	6	V
		V _{CC} = 2 V	1.5			1.5			
ViH	High-level input voltage	$V_{CC} = 4.5 \text{ V}$	3.15			3.15			V
		V _{CC} = 6 V	4.2		7	4.2			
		V _{CC} = 2 V		Ą	0.5			0.5	
VIL	Low-level input voltage	$V_{CC} = 4.5 \text{ V}$		Q'	1.35			1.35	V
		V _{CC} = 6 V		5	1.8			1.8	
٧ı	Input voltage		0	5	VCC	0		VCC	V
٧o	Output voltage		0		VCC	0		VCC	V
		V _{CC} = 2 V	Q		1000			1000	
t _t	Input transition (rise and fall) time	$V_{CC} = 4.5 V$			500			500	ns
		V _{CC} = 6 V			400			400	
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAD	AMETED	TEST OF	NUDITIONS	V	Т	A = 25°C	;	SN54F	IC646	SN74H	IC646	UNIT
PAR	AMETER	lesi co	ONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
				2 V	1.9	1.998		1.9		1.9		
			$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4		
VOH		VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
			$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7	7	3.84		
			$I_{OH} = -7.8 \text{ mA}$	6 V	5.48	5.8		5.2	1/5/	5.34		
				2 V		0.002	0.1		0.1		0.1	
			I _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1	
VOL		$V_I = V_{IH}$ or V_{IL}		6 V		0.001	0.1	3	0.1		0.1	V
			$I_{OL} = 6 \text{ mA}$	4.5 V		0.17	0.26	90	0.4		0.33	
			$I_{OL} = 7.8 \text{ mA}$	6 V		0.15	0.26	y _d	0.4		0.33	
lį	Control inputs	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
loz	A or B	VO = VCC or 0		6 V		±0.01	±0.5		±10		±5	μΑ
Icc		$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
Ci	Control inputs			2 V to 6 V		3	10		10		10	pF

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timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		V	T _A =	25°C	SN54H	C646	SN74H	IC646	LINUT
		VCC	MIN	MAX	MIN	MAX	MIN	MAX	UNII
		2 V		6		4.3		5.5	
fclock	Clock frequency	4.5 V		31		22		27	MHz
		6 V		36		25		31	
		2 V	80		115	151	95		
t_W	Pulse duration, CLKBA or CLKAB high or low	4.5 V	16		23	EL	19		ns
		6 V	14		20	2	16		
		2 V	100		150	,	125		
t _{su}	Setup time, A before CLKAB↑ or B before CLKBA↑	4.5 V	20		30		25		ns
		6 V	17		26		21		
		2 V	5		5		5		
th	Hold time, A after CLKAB↑ or B after CLKBA↑	4.5 V	5		5		5	MIN MAX 5.5 27 31 95 19 16 125 25 21 5	ns
		6 V	5		5		5		



switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 2)

DADAMETER	FROM	то	V	T,	Δ = 25°C	;	SN54H	IC646	SN74H	C646	UNIT
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
			2 V	6	11		4.4		5.5		
f _{max}			4.5 V	31	54		22		27		MHz
			6 V	36	64		25		31		
			2 V		65	180		270		225	
	CLKBA or CLKAB	A or B	4.5 V		18	36		54		45	
			6 V		14	31		46		38	
			2 V		50	135		205		170	
t _{pd}	A or B	B or A	4.5 V		14	27		41		34	ns
			6 V		11	23		35		29	
			2 V		70	190		285		240	
	SBA or SAB†	A or B	4.5 V		20	38		57		48	
			6 V		16	32		48		41	
			2 V		85	245	7	370		305	
t _{en}	ŌĒ	A or B	4.5 V		25	49	032	74		61	ns
			6 V		20	42	70	63		52	
			2 V		85	245	d	370		305	
t _{dis}	ŌĒ	A or B	4.5 V		25	49		74		61	ns
			6 V		20	42		63		52	
			2 V		80	245		370		305	
^t en	DIR	A or B	4.5 V		25	49		74		61	ns
			6 V		20	42		63		52	
			2 V		80	245		370		305	
^t dis	DIR	A or B	4.5 V		25	49		74		61	ns
			6 V		20	42		63		52	
			2 V		28	60		90		75	
t _t		Any	4.5 V		8	12		18		15	ns
			6 V		6	10		15		13	

[†] These parameters are measured with the internal output state of the storage register opposite that of the bus input.

SN54HC646, SN74HC646 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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switching characteristics over recommended operating free-air temperature range, $C_L = 150 \text{ pF}$ (unless otherwise noted) (see Figure 2)

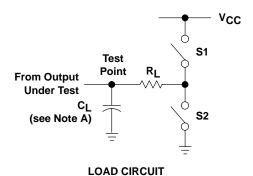
PARAMETER	FROM	то	V	T,	λ = 25°C	;	SN54H	C646	SN74H	C646	UNIT																								
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII																								
			2 V		90	265		400		330																									
	CLKBA or CLKAB	A or B	4.5 V		24	53		80		66																									
			6 V		20	46		68		57																									
			2 V		70	220		335		280																									
^t pd	A or B	B or A	4.5 V		20	44		67		56	ns																								
			6 V		15	38		57		49																									
			2 V		80	275		415		345																									
	SBA or SAB†	A or B	4.5 V		24	55	ć	83		69																									
			6 V		20	47	C)	70		60																									
			2 V		113	330	20	500		410																									
	ŌĒ	A or B	4.5 V		33	66) V	100		82																									
			6 V		27	57	/	85		71	ns																								
t _{en}			2 V		113	330		500		410	115																								
	DIR	A or B	4.5 V		33	66		100		82																									
			6 V		27	57		85		71																									
			2 V		45	210		315		265																									
t _t		Any	Any	Any	Any	Any	Any	Any	Any	Any	Any 4	Any	Any '	Any	4.5 V		17	42		63		53	ns												
			6 V		13	36		53		43																									

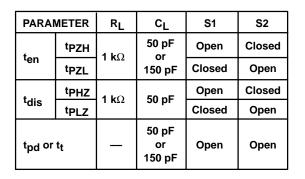
[†] These parameters are measured with the internal output state of the storage register opposite that of the bus input.

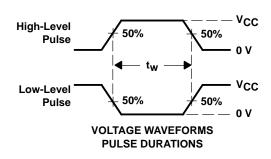
operating characteristics, $T_A = 25^{\circ}C$

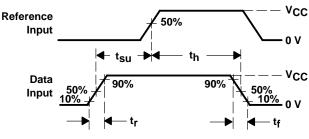
	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load	50	pF

PARAMETER MEASUREMENT INFORMATION

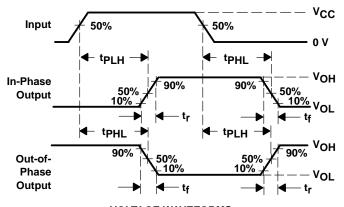


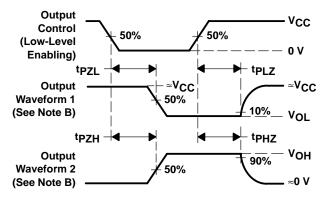






VOLTAGE WAVEFORMS
SETUP AND HOLD AND INPUT RISE AND FALL TIMES





VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f = 6$ ns.
- D. For clock inputs, f_{max} is measured when the input duty cycle is 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLz and tpHz are the same as tdis.
- G. tpzL and tpzH are the same as ten.
- H. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
SN74HC646DW	Obsolete	Production	SOIC (DW) 24	-	-	Call TI	Call TI	-40 to 85	HC646
SN74HC646DWR	Active	Production	SOIC (DW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC646
SN74HC646DWR.A	Active	Production	SOIC (DW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC646

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

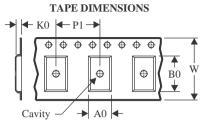
⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

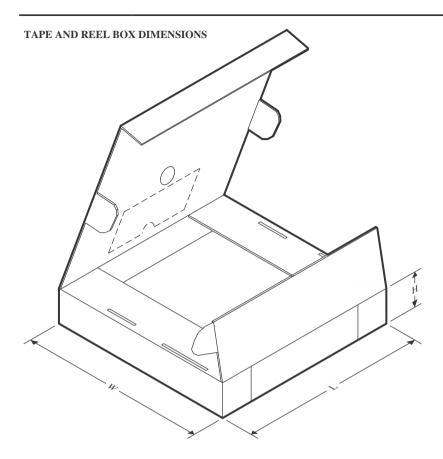


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC646DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

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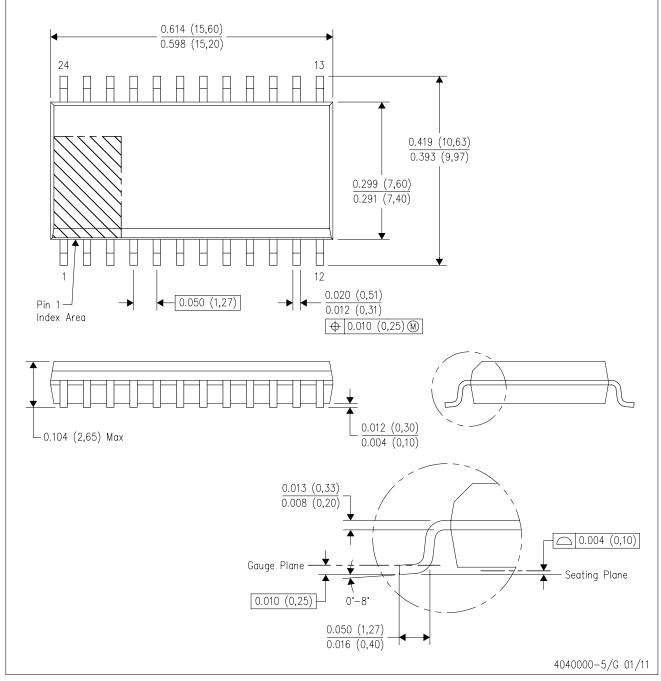


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC646DWR	SOIC	DW	24	2000	350.0	350.0	43.0

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



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